

HVD138A

Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G0426-0100 (Previous: ADE-208-1589) Rev.1.00 Dec 07, 2004

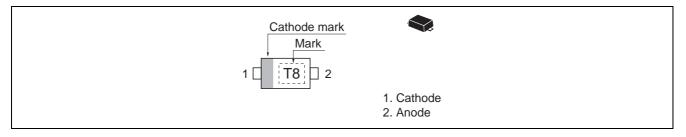
Features

- Adopting the trench structure improves low capacitance.(C = 0.85 pF max)
- Low forward resistance. (rf = $1.1 \Omega \max$)
- Low operation current.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD138A	Т8	SFP

Pin Arrangement





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Reverse voltage	V _R	30	V
Forward current	I _F	100	mA
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

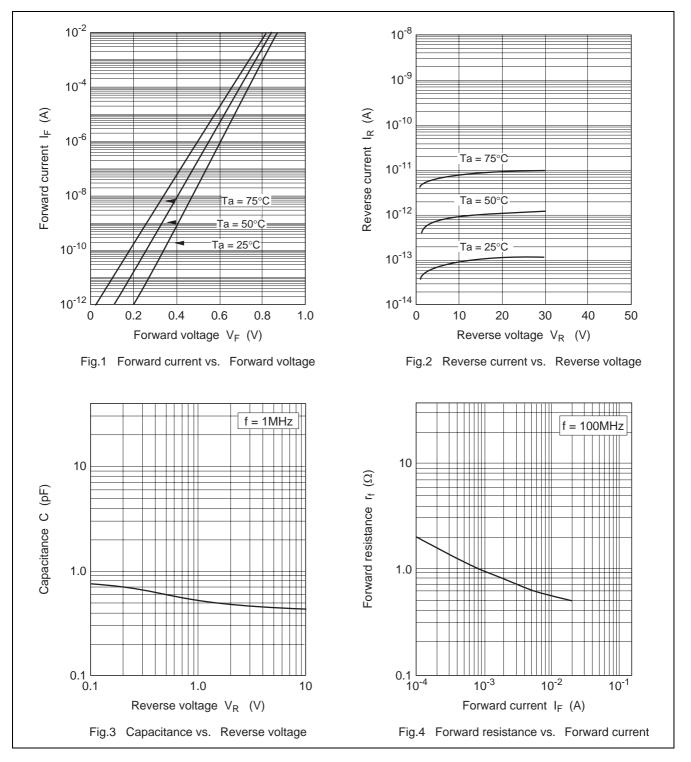
(Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	-	—	10	nA	V _R = 25 V
Forward voltage	VF	-	—	0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	-	—	0.85	pF	$V_R = 1 V$, f = 1 MHz
Forward resistance	r _f	_	—	1.1	Ω	I _F = 2 mA, f = 100 MHz

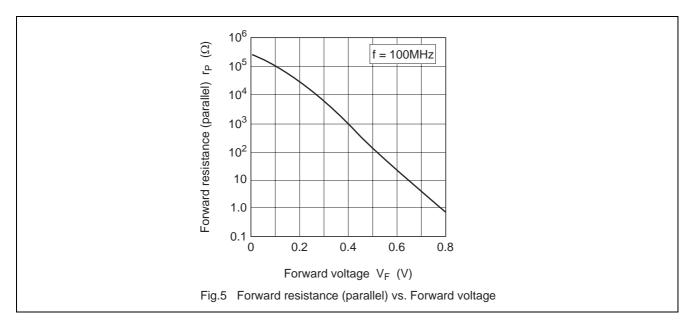
Note: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.



Main Characteristic

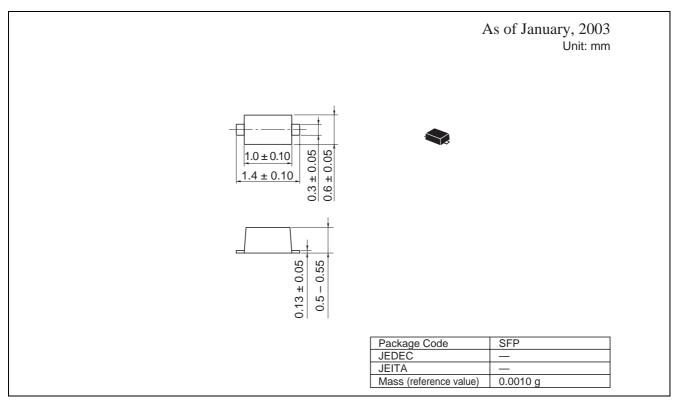








Package Dimensions





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